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BIEE-010

## B.Tech. - VIEP - ELECTRICAL ENGINEERING (BTELVI)

## $\square \square 2 \square 3$ Term-End Examination

June, 2018

## BIEE-010 : MICROCONTROLLERS

Time : 3 hours
Maximum Marks : 70
Note: Answer any five questions. All questions carry equal marks. Assume data wherever required.

1. (a) Give differences between $2 \times 3 \frac{1}{2}=7$
(i) Microprocessors and Microcontrollers
(ii) Harvard and Von-Neumann architecture
(b) Draw block diagram of 8051 microcontroller and give brief description of each pin. $\quad 3+4=7$
2. (a) Write the differences between assembly language and machine language.
(b) What is stack and bank 1 conflict? How can it be resolved ? Explain the steps involved.
3. (a) Write short notes on addressing modes of the 8051.

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(b) Write a program to multiply the numbers 0 ECH by 25 H using the technique of repeated addition.
4. (a) (i) LEDs are connected to bits P1 and P2. Write an 8051 C program that shows the count from 0 to FFH on the LEDs. $3 \frac{1}{2}$
(ii) How is the TMOD register modified to make each of the timers operate as counters?

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3 \frac{1}{2}
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(b) A square wave is generated at pin P1.2. This square wave is to be sent to a receiver connected in serial form to this 8051 . Write a program for this.
5. (a) Explain what happens if a low-priority interrupt is activated while the 8051 is serving a higher-priority interrupt. 7
(b) How is DAC-0808 interface with MCS-51? Also write a program to generate saw-tooth waveform using this IC.
6. (a) Discuss the role of :
(i) EA pin
(ii) PSEN
(iii) P0 and P2
in providing addresses to the 8051 . 7
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(b) Find the organization and chip capacity for each ROM with the indicated number of address and data pins :
(i) 14 address, 8 data
(ii) 16 address, 8 data
(iii) 12 address, 8 data
7. (a) Explain internal RAM structure of the 8051. What do you understand by bit-addressable and byte-addressable memory?
(b) Write a program to divide a 16 -bit number by an 8-bit number.

